

Control iD

PCB Stack-up and Technical Requirements

Our minimum specifications are as follow:

| | |
|------------------------------------|--------------------------------------|
| Number of layers: | 2 layers |
| Minimum line width (<=): | 8 mils |
| Minimum line spacing/gap (<=): | 8 mils |
| Minimum Annular Ring (<=): | 8 mils |
| Minimum mechanical hole size (<=): | 0,3mm |
| Surface finish: | HASL |
| Electrical Test: | 100% Electrical Test (E-Test) |
| Substrate type: | FR-4 |

PCB Stack-up and files:

| Layer name | Thickness (mm) | File extension |
|---------------------------|----------------|----------------|
| Silkscreen Top (White) | - | *.GTL |
| Soldermask Top (Red) | - | *.GTS |
| Copper Top | 0,036 | *.GTL |
| Dielectric | 1,5 | - |
| Copper Bottom | 0,036 | *.GBL |
| Soldermask Bottom (Red) | - | *.GBS |
| Silkscreen Bottom (White) | - | *.GBO |
| Total thickness | 1,572 | |

| File type | File Extension |
|--|----------------|
| Stencil top | *.GTP |
| Board outline | *.GM1 |
| Drill information (2.5 / Leading zero suppression) | *.TXT |
| (All vias are 100% pass through) | |